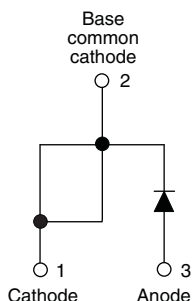


## Hyperfast Rectifier, 30 A FRED Pt®



TO-247AC modified



### FEATURES

- Hyperfast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- Single diode device
- Compliant to RoHS Directive 2002/95/EC
- Designed and qualified according to JEDEC-JESD47
- Halogen-free according to IEC 61249-2-21 definition (-N3 only)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**  
Available

### PRODUCT SUMMARY

|                 |                            |
|-----------------|----------------------------|
| Package         | TO-247AC modified (2 pins) |
| $I_{F(AV)}$     | 30 A                       |
| $V_R$           | 600 V                      |
| $V_F$ at $I_F$  | 2.6 V                      |
| $t_{rr}$ typ.   | See Recovery table         |
| $T_J$ max.      | 175 °C                     |
| Diode variation | Single die                 |

### DESCRIPTION/APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

### ABSOLUTE MAXIMUM RATINGS

| PARAMETER                                   | SYMBOL         | TEST CONDITIONS       | VALUES      | UNITS |
|---------------------------------------------|----------------|-----------------------|-------------|-------|
| Peak repetitive reverse voltage             | $V_{RRM}$      |                       | 600         | V     |
| Average rectified forward current           | $I_{F(AV)}$    | $T_C = 116\text{ °C}$ | 30          | A     |
| Non-repetitive peak surge current           | $I_{FSM}$      | $T_J = 25\text{ °C}$  | 300         |       |
| Operating junction and storage temperatures | $T_J, T_{Stg}$ |                       | - 65 to 175 | °C    |

### ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)

| PARAMETER                           | SYMBOL        | TEST CONDITIONS                              | MIN. | TYP. | MAX. | UNITS         |
|-------------------------------------|---------------|----------------------------------------------|------|------|------|---------------|
| Breakdown voltage, blocking voltage | $V_{BR}, V_R$ | $I_R = 100\text{ }\mu\text{A}$               | 600  | -    | -    | V             |
| Forward voltage                     | $V_F$         | $I_F = 30\text{ A}$                          | -    | 2.0  | 2.6  |               |
|                                     |               | $I_F = 30\text{ A}, T_J = 150\text{ °C}$     | -    | 1.34 | 1.75 |               |
| Reverse leakage current             | $I_R$         | $V_R = V_R$ rated                            | -    | 0.3  | 50   | $\mu\text{A}$ |
|                                     |               | $T_J = 150\text{ °C}, V_R = V_R$ rated       | -    | 60   | 500  |               |
| Junction capacitance                | $C_T$         | $V_R = 600\text{ V}$                         | -    | 33   | -    | pF            |
| Series inductance                   | $L_S$         | Measured lead to lead 5 mm from package body | -    | 3.5  | -    | nH            |

**DYNAMIC RECOVERY CHARACTERISTICS** ( $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise specified)

| PARAMETER               | SYMBOL    | TEST CONDITIONS                                                                  | MIN. | TYP. | MAX. | UNITS |
|-------------------------|-----------|----------------------------------------------------------------------------------|------|------|------|-------|
| Reverse recovery time   | $t_{rr}$  | $I_F = 1.0\text{ A}$ , $dI_F/dt = 50\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$ | -    | 28   | 35   | ns    |
|                         |           | $T_J = 25\text{ }^{\circ}\text{C}$                                               | -    | 31   | -    |       |
|                         |           | $T_J = 125\text{ }^{\circ}\text{C}$                                              | -    | 77   | -    |       |
| Peak recovery current   | $I_{RRM}$ | $T_J = 25\text{ }^{\circ}\text{C}$                                               | -    | 3.5  | -    | A     |
|                         |           | $T_J = 125\text{ }^{\circ}\text{C}$                                              | -    | 7.7  | -    |       |
| Reverse recovery charge | $Q_{rr}$  | $T_J = 25\text{ }^{\circ}\text{C}$                                               | -    | 65   | -    | nC    |
|                         |           | $T_J = 125\text{ }^{\circ}\text{C}$                                              | -    | 345  | -    |       |

**THERMAL - MECHANICAL SPECIFICATIONS**

| PARAMETER                                       | SYMBOL         | TEST CONDITIONS                            | MIN.         | TYP. | MAX.       | UNITS                       |
|-------------------------------------------------|----------------|--------------------------------------------|--------------|------|------------|-----------------------------|
| Maximum junction and storage temperature range  | $T_J, T_{Stg}$ |                                            | - 65         | -    | 175        | $^{\circ}\text{C}$          |
| Thermal resistance, junction to case per leg    | $R_{thJC}$     |                                            | -            | 0.5  | 0.9        | $^{\circ}\text{C}/\text{W}$ |
| Thermal resistance, junction to ambient per leg | $R_{thJA}$     | Typical socket mount                       | -            | -    | 70         |                             |
| Thermal resistance, case to heatsink            | $R_{thCS}$     | Mounting surface, flat, smooth and greased | -            | 0.4  | -          |                             |
| Weight                                          |                |                                            | -            | 6.0  | -          | g                           |
|                                                 |                |                                            | -            | 0.22 | -          | oz.                         |
| Mounting torque                                 |                |                                            | 6.0<br>(5.0) | -    | 12<br>(10) | kgf · cm<br>(lbf · in)      |
| Marking device                                  |                | Case style TO-247AC modified               | 30EPH06      |      |            |                             |

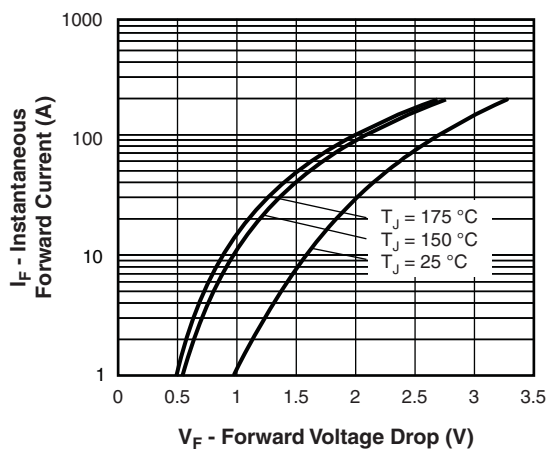


Fig. 1 - Typical Forward Voltage Drop Characteristics

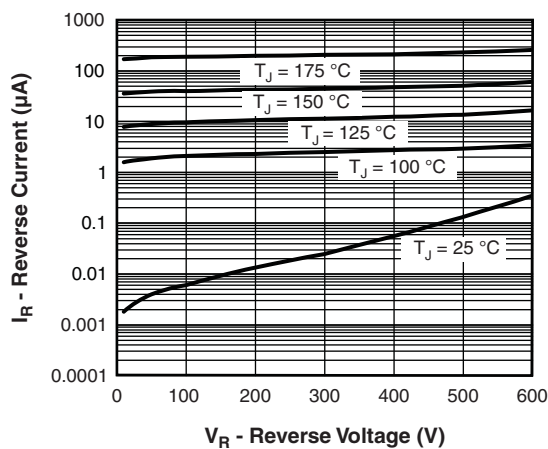


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

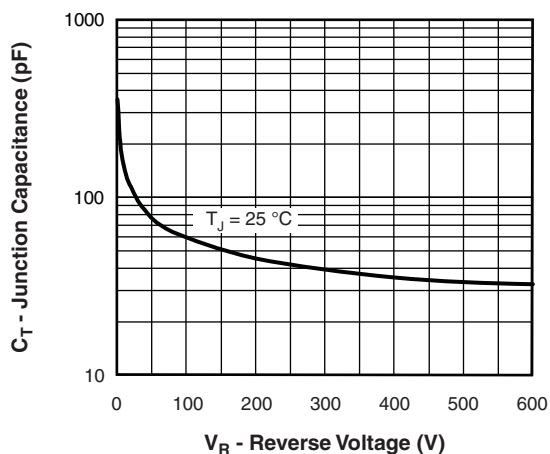
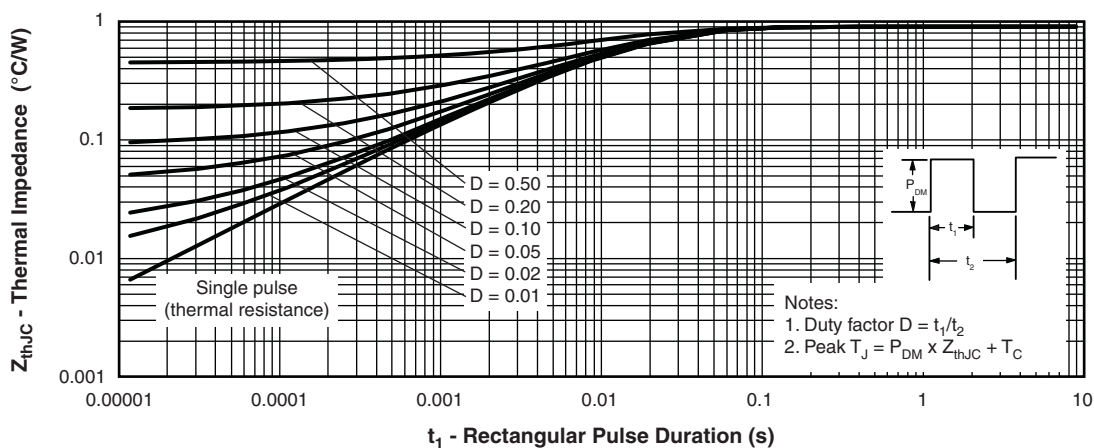


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

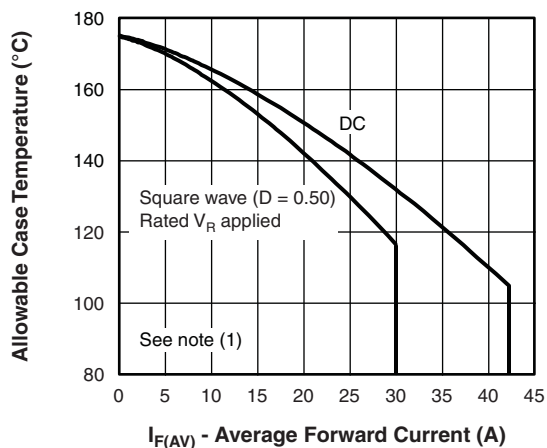


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

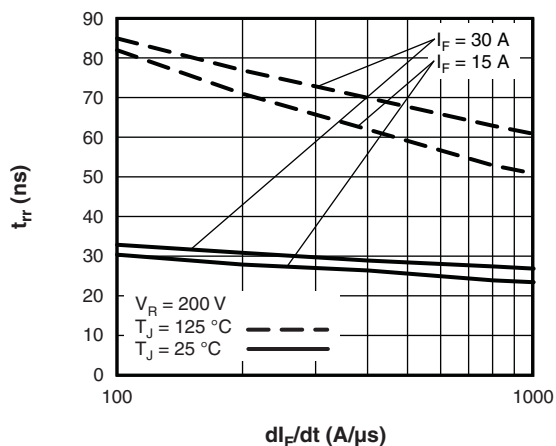


Fig. 7 - Typical Reverse Recovery Time vs.  $dI_F/dt$

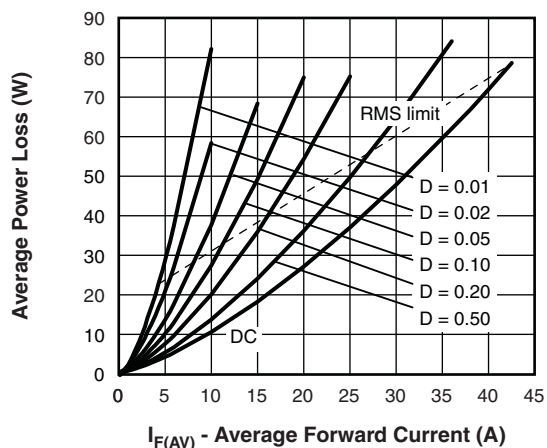


Fig. 6 - Forward Power Loss Characteristics

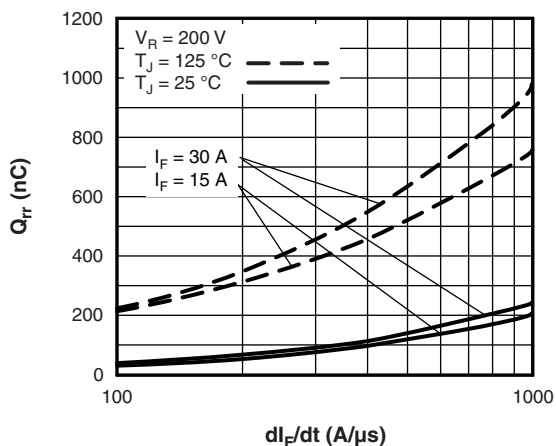


Fig. 8 - Typical Stored Charge vs.  $dI_F/dt$

#### Note

- (1) Formula used:  $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$ ;  
 $P_d$  = Forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);  
 $P_{dREV}$  = Inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1}$  = Rated  $V_R$

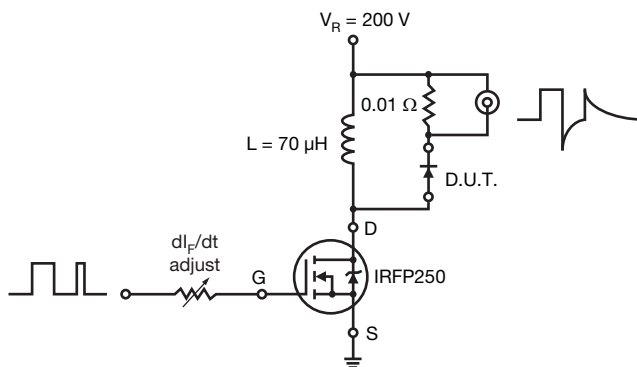


Fig. 9 - Reverse Recovery Parameter Test Circuit

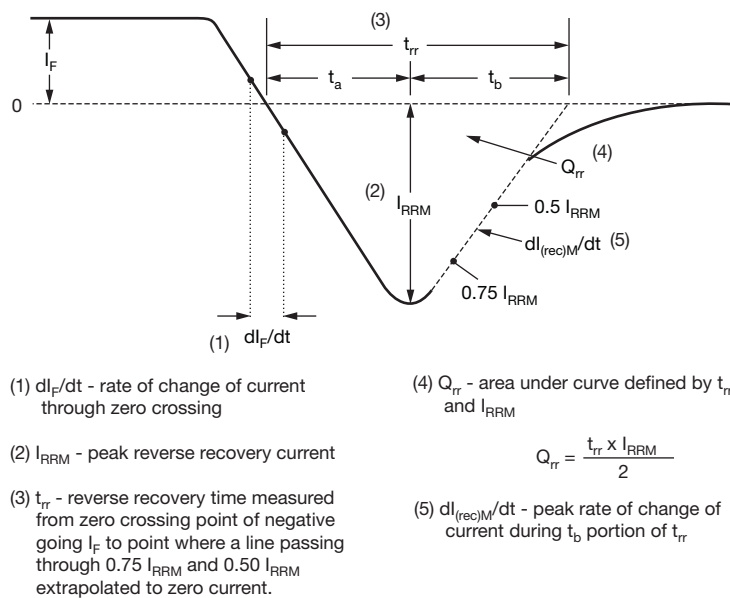


Fig. 10 - Reverse Recovery Waveform and Definitions

**ORDERING INFORMATION TABLE**

|             |            |           |          |          |          |           |            |
|-------------|------------|-----------|----------|----------|----------|-----------|------------|
| Device code | <b>VS-</b> | <b>30</b> | <b>E</b> | <b>P</b> | <b>H</b> | <b>06</b> | <b>PbF</b> |
|             | 1          | 2         | 3        | 4        | 5        | 6         | 7          |

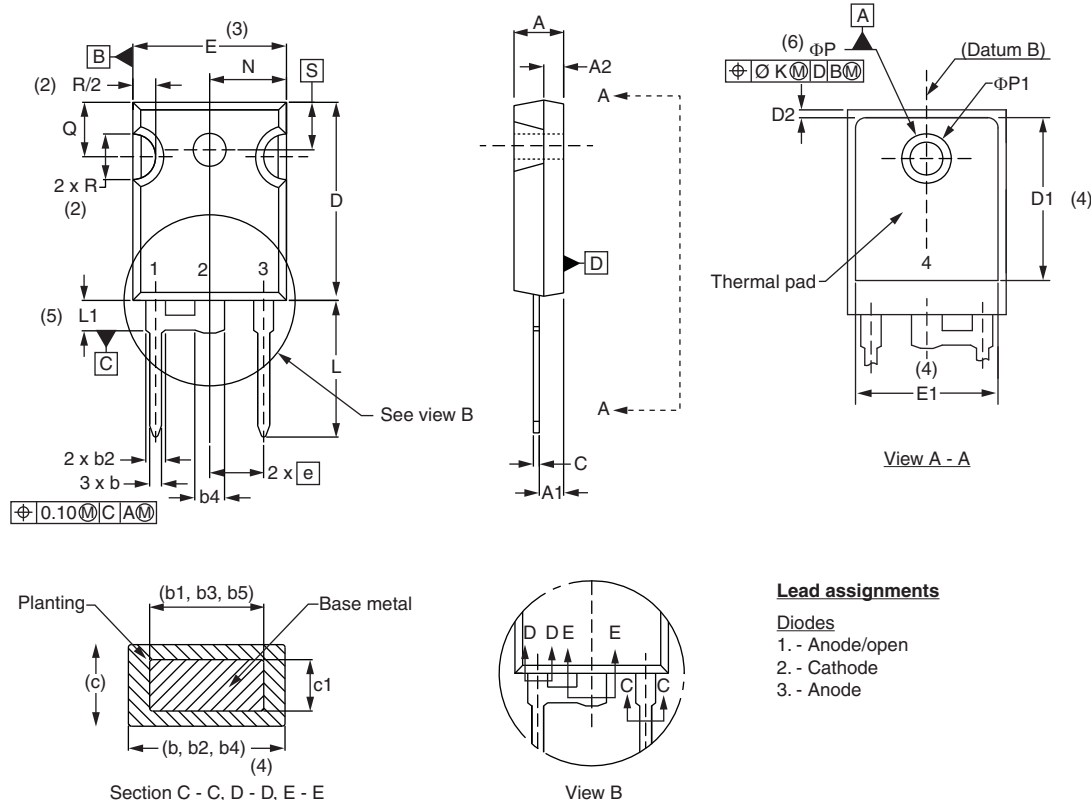
- 1** - Vishay Semiconductors product
- 2** - Current rating (30 = 30 A)
- 3** - Circuit configuration:  
E = Single diode
- 4** - Package:  
P = TO-247AC modified
- 5** - H = Hyperfast recovery
- 6** - Voltage rating (06 = 600 V)
- 7** - Environmental digit:  
PbF = Lead (Pb)-free and RoHS compliant  
-N3 = Halogen-free, RoHS compliant and totally lead (Pb)-free

| <b>ORDERING INFORMATION</b> (Example) |                         |                               |                              |
|---------------------------------------|-------------------------|-------------------------------|------------------------------|
| <b>PREFERRED P/N</b>                  | <b>QUANTITY PER T/R</b> | <b>MINIMUM ORDER QUANTITY</b> | <b>PACKAGING DESCRIPTION</b> |
| VS-30EPH06PbF                         | 25                      | 500                           | Antistatic plastic tube      |
| VS-30EPH06-N3                         | 25                      | 500                           | Antistatic plastic tube      |

| <b>LINKS TO RELATED DOCUMENTS</b> |                       |                                                                        |
|-----------------------------------|-----------------------|------------------------------------------------------------------------|
| Dimensions                        |                       | <a href="http://www.vishay.com/doc?95253">www.vishay.com/doc?95253</a> |
| Part marking information          | TO-247AC modified PbF | <a href="http://www.vishay.com/doc?95255">www.vishay.com/doc?95255</a> |
|                                   | TO-247AC modified -N3 | <a href="http://www.vishay.com/doc?95442">www.vishay.com/doc?95442</a> |



### DIMENSIONS in millimeters and inches



#### Lead assignments

##### Diodes

1. - Anode/open
2. - Cathode
3. - Anode

| SYMBOL | MILLIMETERS |       | INCHES |       | NOTES |
|--------|-------------|-------|--------|-------|-------|
|        | MIN.        | MAX.  | MIN.   | MAX.  |       |
| A      | 4.65        | 5.31  | 0.183  | 0.209 |       |
| A1     | 2.21        | 2.59  | 0.087  | 0.102 |       |
| A2     | 1.50        | 2.49  | 0.059  | 0.098 |       |
| b      | 0.99        | 1.40  | 0.039  | 0.055 |       |
| b1     | 0.99        | 1.35  | 0.039  | 0.053 |       |
| b2     | 1.65        | 2.39  | 0.065  | 0.094 |       |
| b3     | 1.65        | 2.37  | 0.065  | 0.094 |       |
| b4     | 2.59        | 3.43  | 0.102  | 0.135 |       |
| b5     | 2.59        | 3.38  | 0.102  | 0.133 |       |
| c      | 0.38        | 0.86  | 0.015  | 0.034 |       |
| c1     | 0.38        | 0.76  | 0.015  | 0.030 |       |
| D      | 19.71       | 20.70 | 0.776  | 0.815 | 3     |
| D1     | 13.08       | -     | 0.515  | -     | 4     |

| SYMBOL    | MILLIMETERS |       | INCHES    |       | NOTES |
|-----------|-------------|-------|-----------|-------|-------|
|           | MIN.        | MAX.  | MIN.      | MAX.  |       |
| D2        | 0.51        | 1.30  | 0.020     | 0.051 |       |
| E         | 15.29       | 15.87 | 0.602     | 0.625 | 3     |
| E1        | 13.72       | -     | 0.540     | -     |       |
| e         | 5.46 BSC    |       | 0.215 BSC |       |       |
| $\Phi K$  | 2.54        |       | 0.010     |       |       |
| L         | 14.20       | 16.10 | 0.559     | 0.634 |       |
| L1        | 3.71        | 4.29  | 0.146     | 0.169 |       |
| N         | 7.62 BSC    |       | 0.3       |       |       |
| $\Phi P$  | 3.56        | 3.66  | 0.14      | 0.144 |       |
| $\Phi P1$ | -           | 6.98  | -         | 0.275 |       |
| Q         | 5.31        | 5.69  | 0.209     | 0.224 |       |
| R         | 4.52        | 5.49  | 1.78      | 0.216 |       |
| S         | 5.51 BSC    |       | 0.217 BSC |       |       |

#### Notes

- (1) Dimensioning and tolerance per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6)  $\Phi P$  to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC outline TO-247 with exception of dimension c



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